L Number	Hits	Search Text	DB	Time stamp
1	3579	carrier and (solder near (ball or bump)) and (electronic or ic or chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 18:14
2	1602	(carrier and (solder near (ball or bump)) and (electronic or ic or chip or die)) and (@ad<19990625)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 18:15
3	149	((carrier and (solder near (ball or bump)) and (electronic or ic or chip or die)) and (@ad<19990625)) and 257/778.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 17:55
4	0	6515355.URPN.	USPAT	2004/07/20 16:25
5	0	6515355.URPN.	USPAT	2004/07/20 16:25
6	7	("4996587" | "5222014" | "5569497" | "5811879" | "5956233" | "5956605" | "6090530").PN.	USPAT	2004/07/20 16:25
7	148	5222014.URPN.	USPAT	2004/07/20 16:33
8	5	("4672421" | "4878611" | "5011066" | "5036431" | "5060844").PN.	USPAT	2004/07/20 16:33
9	0	("49549510").PN.	USPAT	2004/07/20 17:50
10	1	("4959510").PN.	USPAT	2004/07/20 17:55
11	82	((carrier and (solder near (ball or bump)) and (electronic or ic or chip or die)) and (@ad<19990625)) and ((pth or (through adj hole) or (plated near hole)) with pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 17:56
12	6	(((carrier and (solder near (ball or bump)) and (electronic or ic or chip or die)) and (@ad<19990625)) and ((pth or (through adj hole) or (plated near hole)) with pad)) and (((thick or large or big) and (small or thin or narrow or fine)) with pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 18:25
13	383	(semiconductor or chip or die) and (traces or trace) and (((thick or large or big) and (small or thin or narrow or fine)) with pad)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 18:01
14	166	((semiconductor or chip or die) and (traces or trace) and (((thick or large or big) and (small or thin or narrow or fine)) with pad)) and (@ad<19990625)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 18:01
15	166	(((semiconductor or chip or die) and (traces or trace) and (((thick or large or big) and (small or thin or narrow or fine)) with pad) and (@ad<19990625)) not 5222014.URPN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 18:07
16	64	((((semiconductor or chip or die) and (traces or trace) and (((thick or large or big) and (small or thin or narrow or fine)) with pad) and (@ad<19990625)) not 5222014.URPN.) and carrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 18:14
17	23846	(chip and die) and (@ad<19990625)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 19:46

18	15648	(solder near (ball or bump)) and (electronic or ic or chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 18:15
19	7316	((solder near (ball or bump)) and (electronic or ic or chip or die)) and (@ad<19990625)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 18:15
20	8	(((carrier and (solder near (ball or bump)) and (electronic or ic or chip or die)) and (@ad<19990625)) and ((pth or (through adj hole) or (plated near hole)) with pad)) and (((thick or large or big) and (small or thin or narrow or fine)) with (ball or balls or bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 18:25
22	0	"406198936"	JPO; DERWENT	2004/07/20 18:26
23	1	"6198936"	JPO; DERWENT	2004/07/20 18:26
24	2	"60198936"	JPO; DERWENT	2004/07/20 18:50
25	0	("55593666").PN.	USPAT	2004/07/20 18:50
26	1	("5559366").PN.	USPAT	2004/07/20 18:53
27	1	("5939774").PN.	USPAT	2004/07/20 18:54
28	1	("6097097").PN.	USPAT	2004/07/20 18:54
21	393	(((solder near (ball or bump)) and (electronic or ic or chip or die)) and (@ad<19990625)) and (((thick or large or big) and (small or thin or narrow or fine)) with (ball or balls or bump))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 18:55
29	3	((chip and die) and (@ad<19990625)) and ((wireand pad) near barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 19:46
30	0	((chip and die) and (@ad<19990625)) and ((wire and pad) near barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 19:47
31	0	((chip and die) and (@ad<19990625)) and (pad near (barrier and wire))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 19:48
32	3	(chip or die) and (pad near (barrier and wire))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/07/20 19:51
33	0	6759597.URPN.	USPAT	2004/07/20 19:50
34	0	6759597.URPN.	USPAT	2004/07/20 19:50
35	3	("5100835" | "5249728" | "5618754").PN.	USPAT	2004/07/20 19:50
36	1	("6162664").PN.	USPAT	2004/07/20 19:51